

US00D568837S

(12) **United States Design Patent**  
**Hosaka**

(10) **Patent No.:** **US D568,837 S**

(45) **Date of Patent:** **\*\* May 13, 2008**

(54) **SEMICONDUCTOR WAFER DELIVERY APPARATUS**

(75) Inventor: **Hiroki Hosaka**, Nirasaki (JP)

(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/242,547**

(22) Filed: **Nov. 14, 2005**

(30) **Foreign Application Priority Data**

Aug. 12, 2005 (JP) ..... 2005-023556

(51) **LOC (8) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
134/110; 396/611; 414/331.15, 411, 416.03;  
700/213

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor wafer delivery apparatus, as shown and described.

**DESCRIPTION**

FIG. 1 is a front elevational view of a semiconductor wafer delivery apparatus, showing my design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a left side elevational view thereof;

FIG. 4 is a right side elevational view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof;

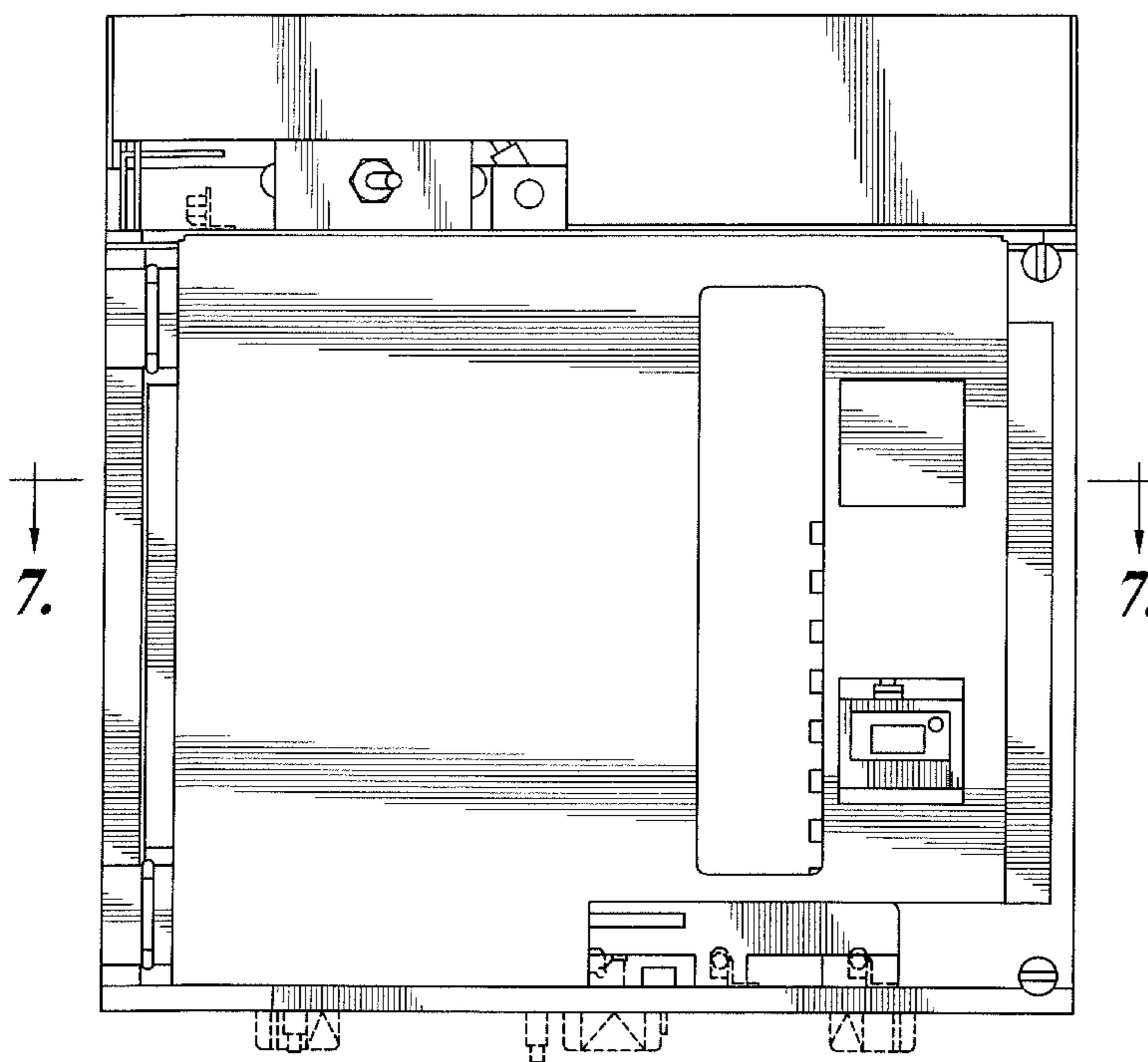
FIG. 7 is a cross-sectional view taken along line 7—7 in FIG. 5;

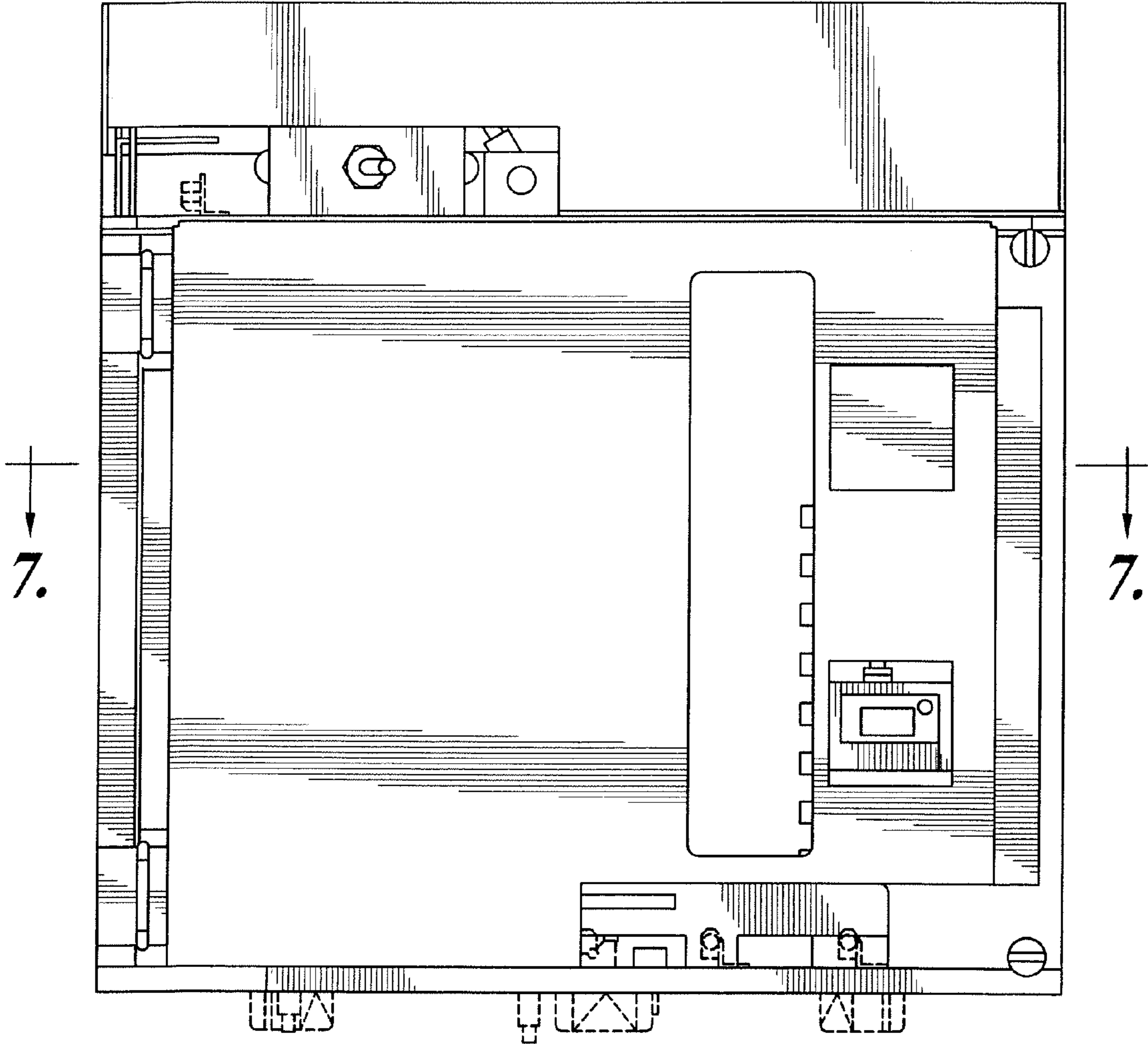
FIG. 8 is a top and right front perspective view thereof; and,

FIG. 9 is a top and left rear perspective view thereof.

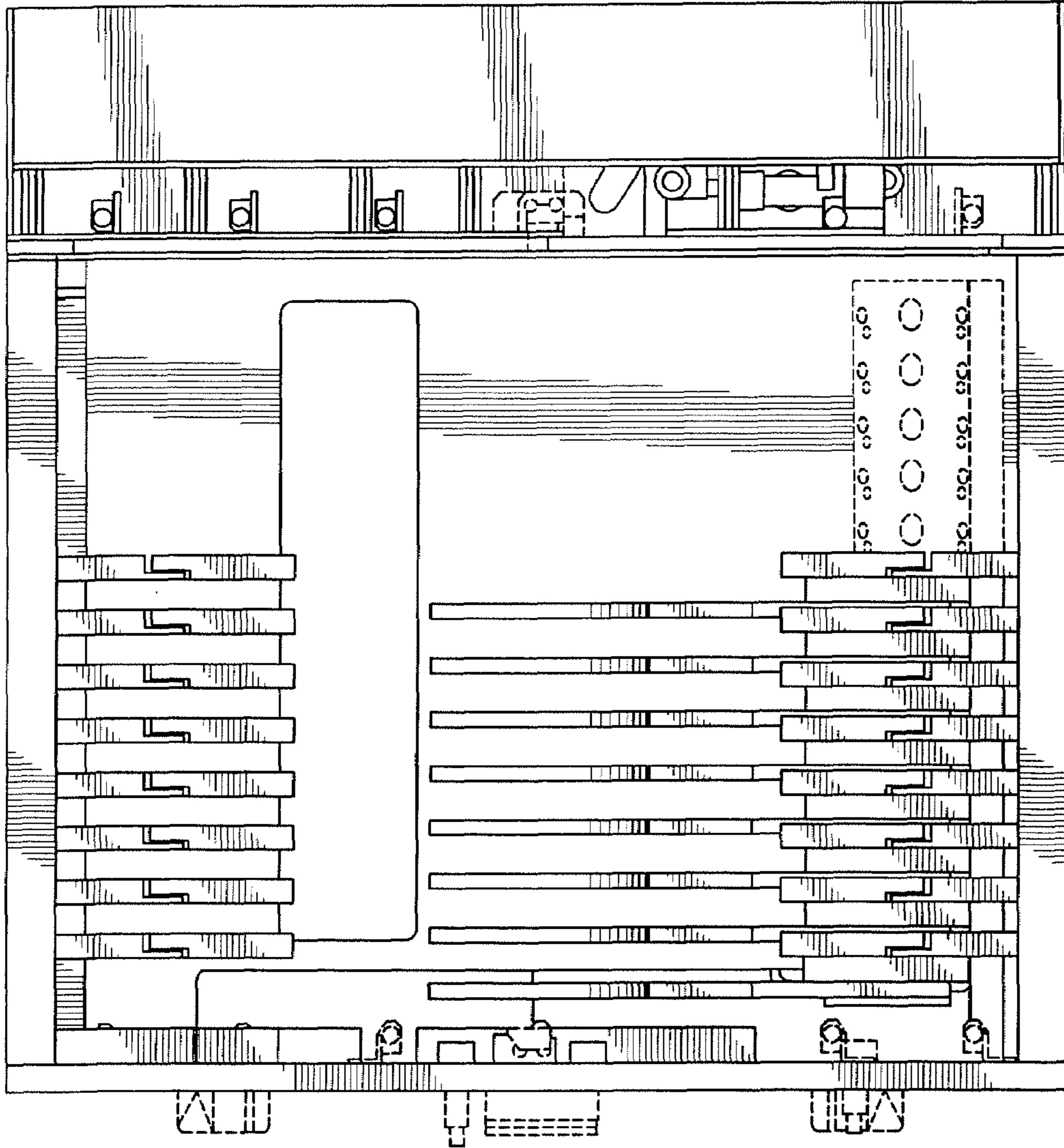
The broken lines represent unclaimed subject matter.

**1 Claim, 9 Drawing Sheets**

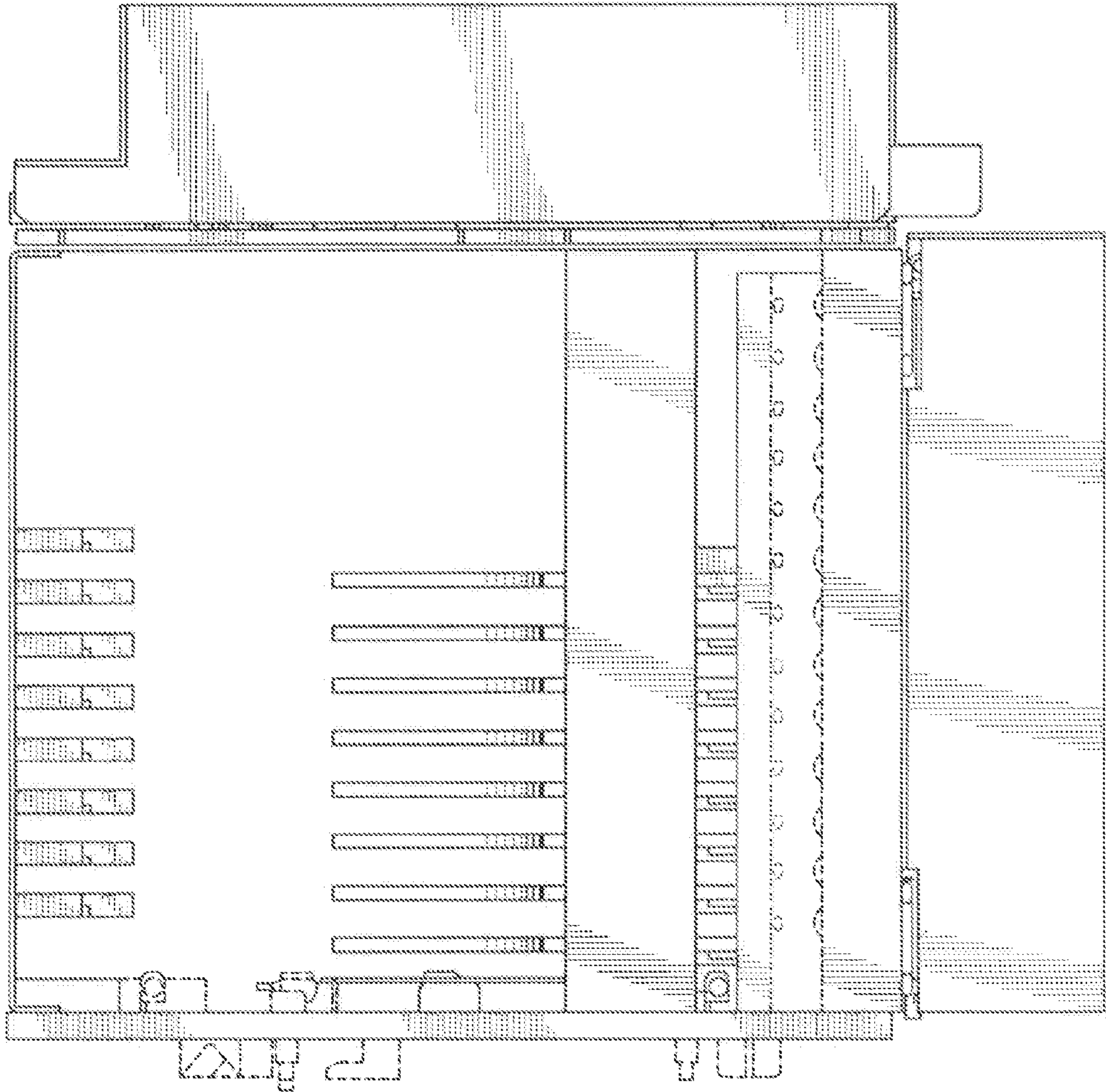




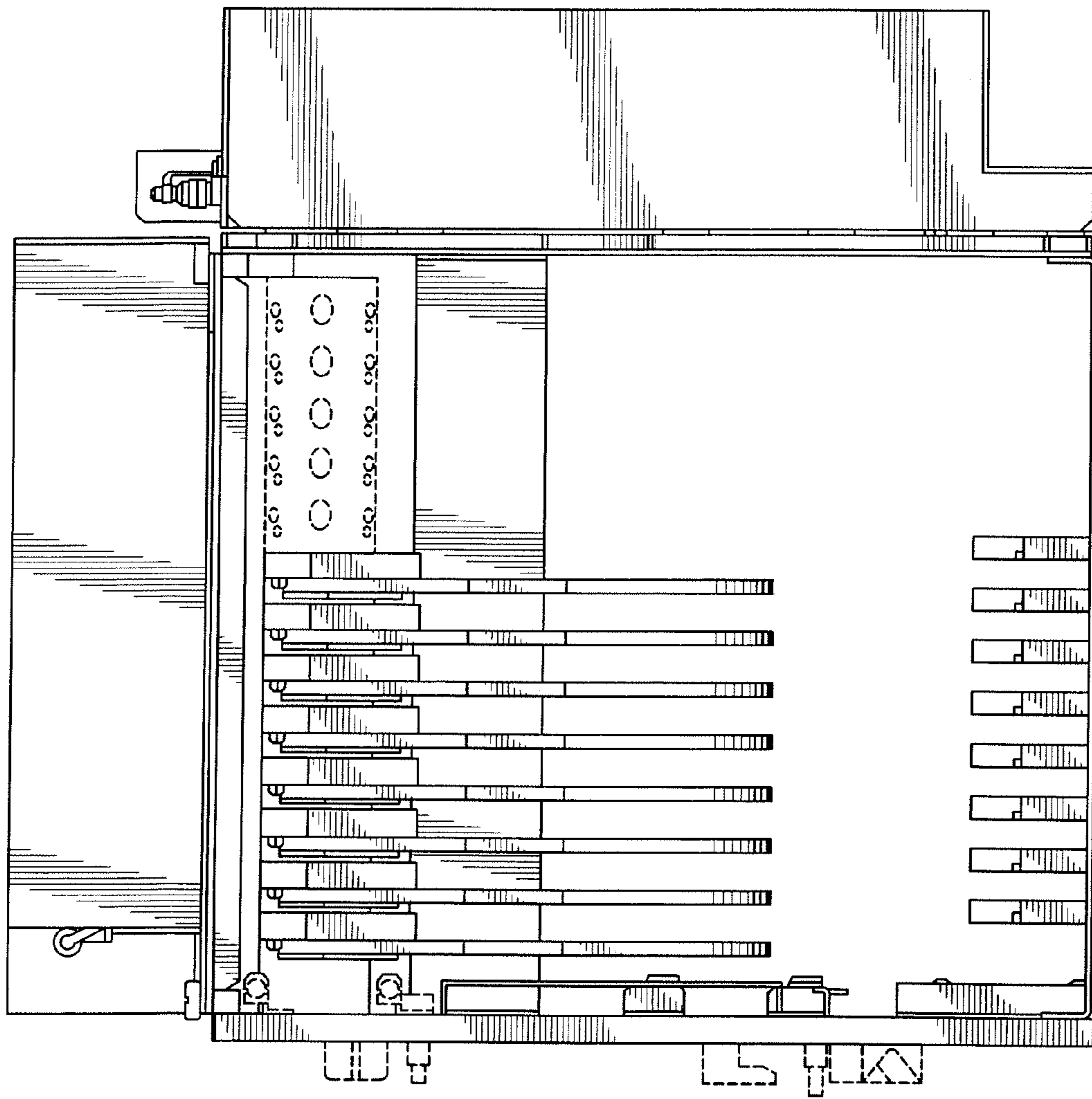
*Fig. 1*



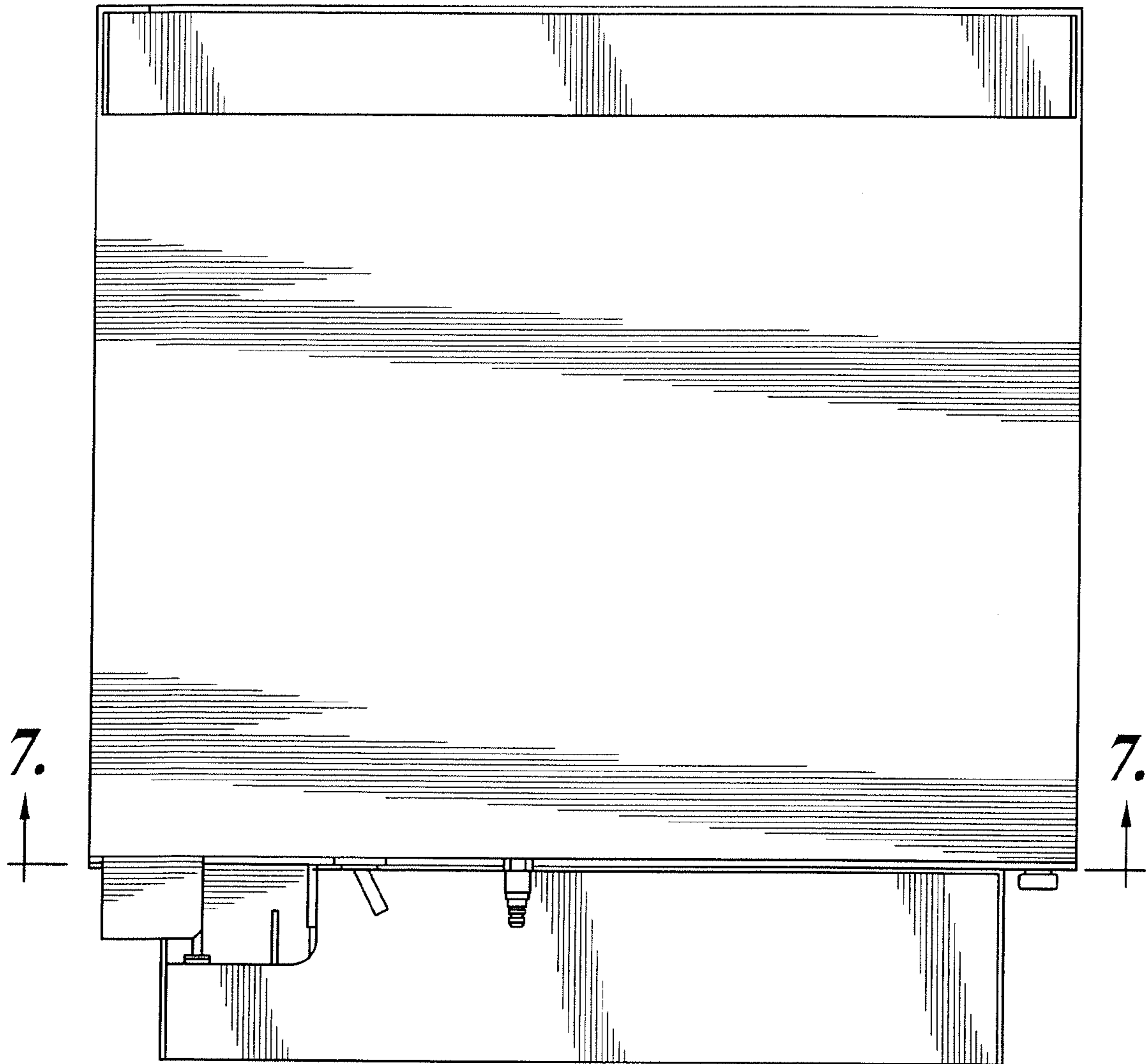
*Fig. 2*



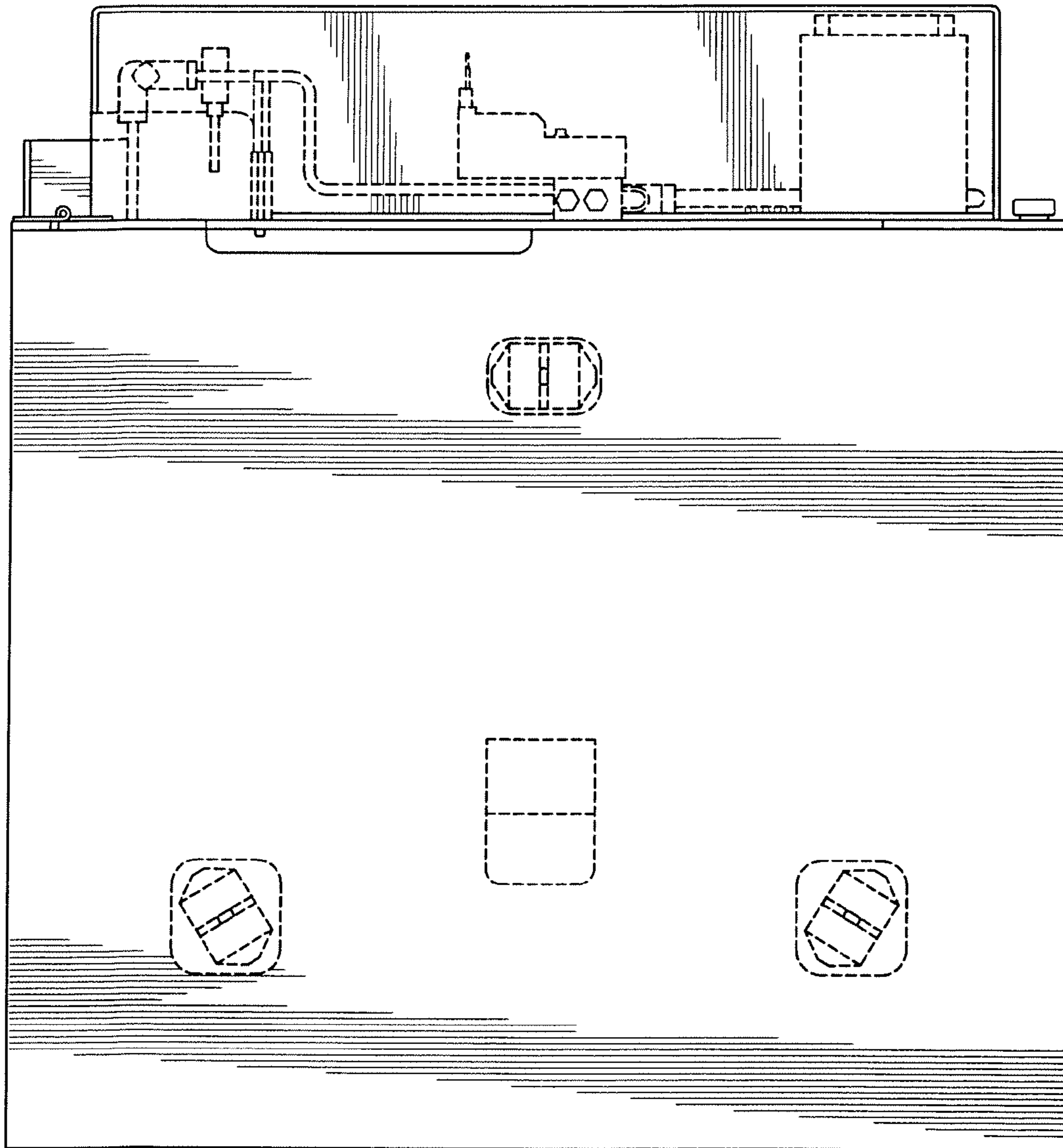
*Fig. 3*



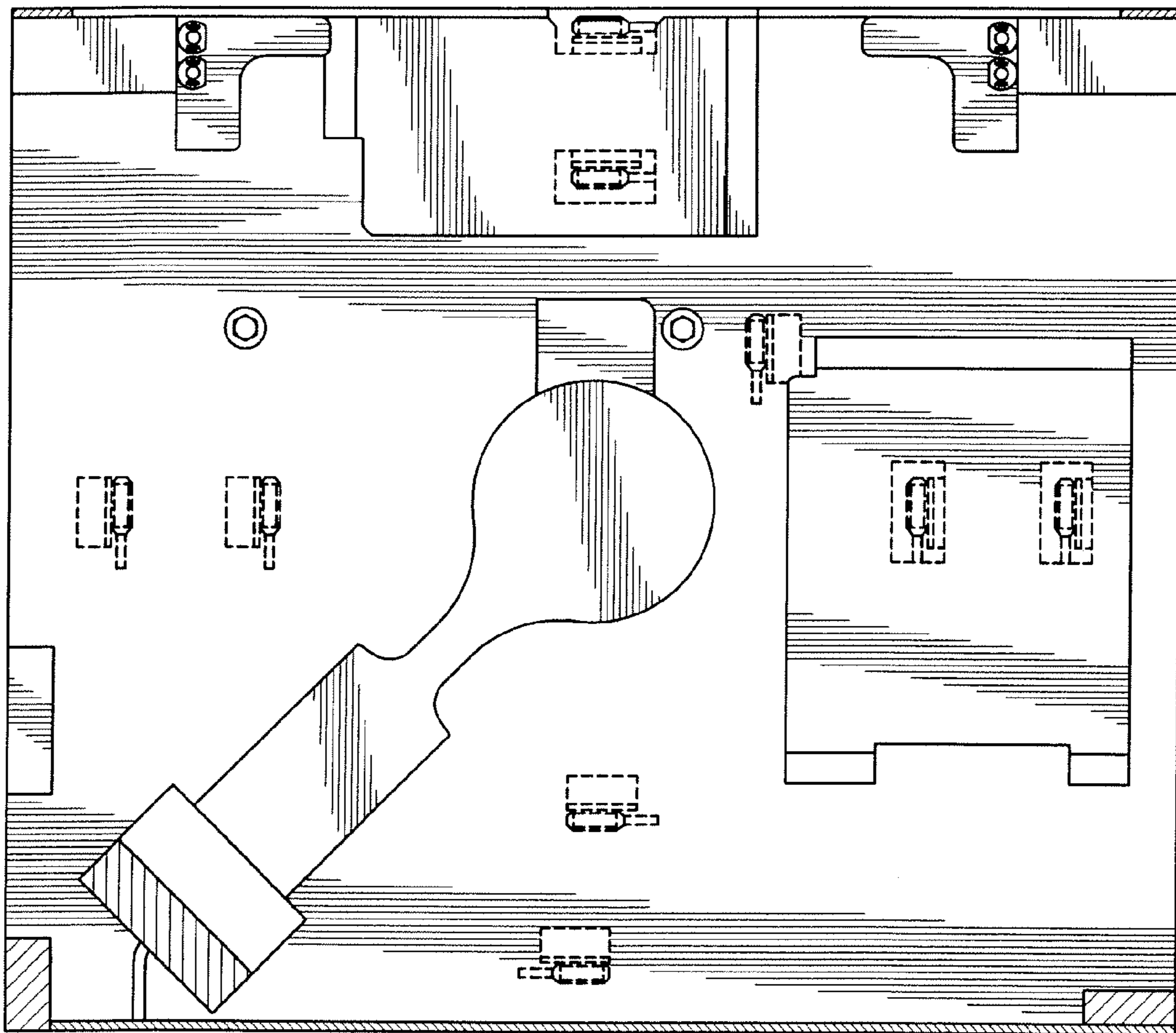
*Fig. 4*



*Fig. 5*

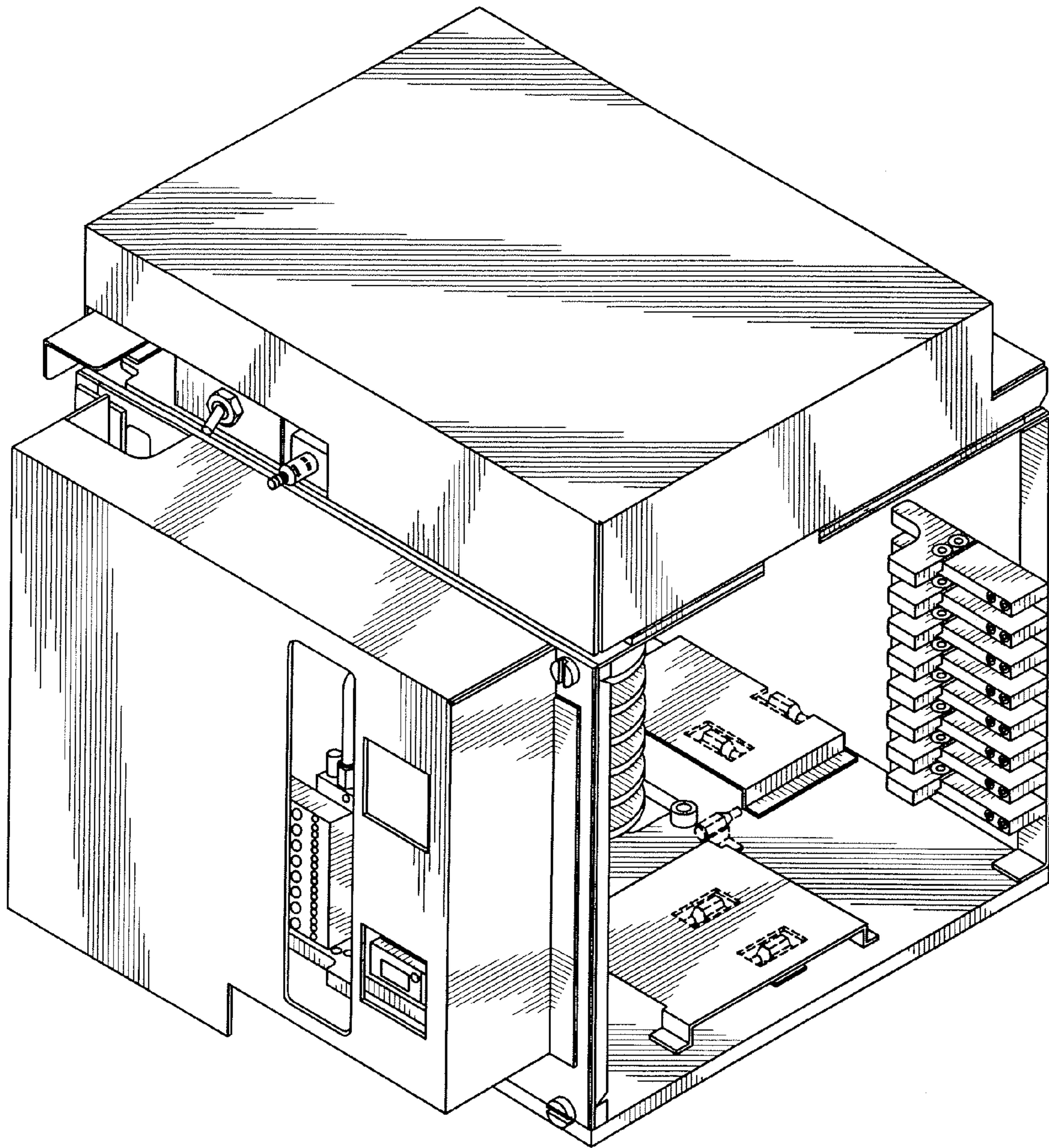


*Fig. 6*

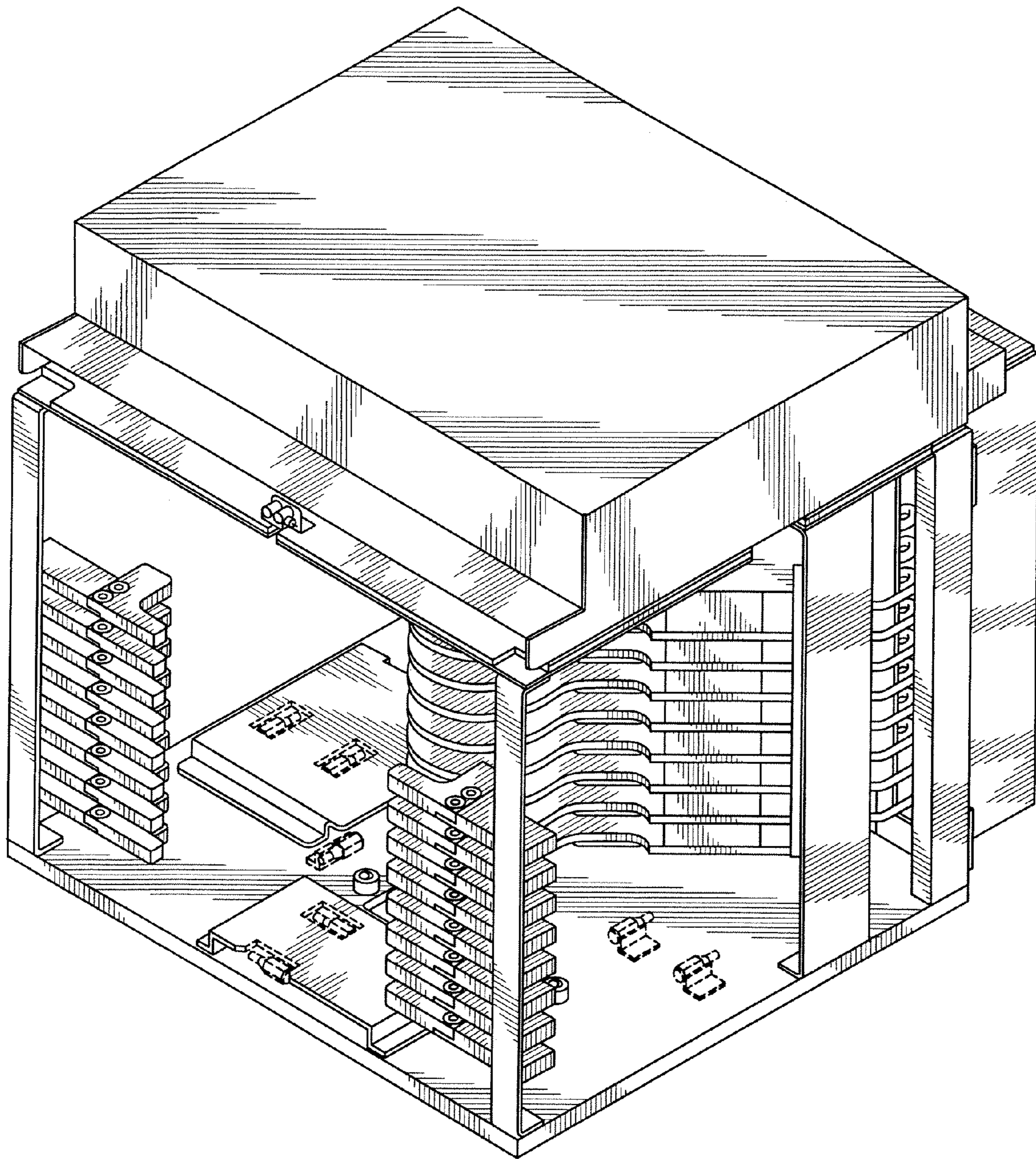


*Fig. 7*





*Fig. 8*



*Fig. 9*

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : Des. 568,837 S  
APPLICATION NO. : 29/242547  
DATED : May 13, 2008  
INVENTOR(S) : Hosaka

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, the Terminal Disclaimer information has been omitted. Item (45) and the Notice information should read as follows:

--(45) **Date of Patent: \*\*\*May 13, 2008**

(\* Notice: This Patent is subject to a terminal disclaimer.--

Signed and Sealed this

Fifth Day of August, 2008

A handwritten signature in black ink that reads "Jon W. Dudas". The signature is written in a cursive style with a large, stylized initial "J".

JON W. DUDAS

*Director of the United States Patent and Trademark Office*